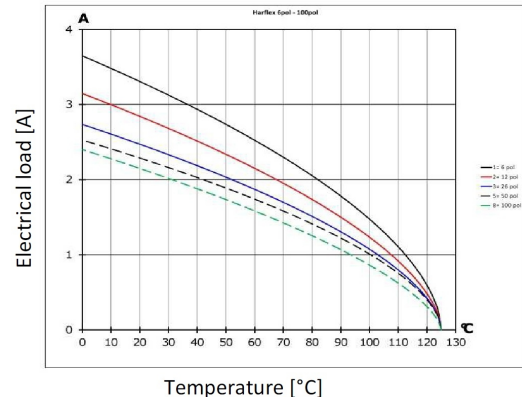


1	2	3	4	5	6	7	8																																								
A	 har-flex[®]straight male connector 			RECOMMENDATION FOR SOLDER PROCESSING Solder paste recommendation The har-flex connectors are solderable with established lead-free SAC / SnNi solder but also leaded solder e.g. SnPb40 PCB pad plating The har-flex connectors are solderable on lead-free pad surfaces like HAL, NiAu, Immersion Sn. Stencil recommendation The solder deposition has to be placed on the pad area of the contact solder tines. Ideally, the solder deposition has the same length-to-width ratio and center point like the PCB pads. The size of the solder stencil apertures is depending on the thickness of the stencil. In general, the thinner stencils will need larger apertures to result in the required volume of solder paste. The minimum required solder paste volume for the signal pins is 0,094mm³, for the hold down it is 0,33mm³. For example, this can be achieved with the following stencil data : <table><tr><td></td><td colspan="3">Signal pins</td></tr><tr><td>Stencil thickness</td><td>PCB pad size</td><td>proposal stencil aperture size</td><td>calculated solder paste volume</td></tr><tr><td>120 µm</td><td>1,1 x 0,8 mm</td><td>1,05 x 0,75 mm</td><td>0,095 mm³</td></tr><tr><td>150 µm</td><td>1,1 x 0,8 mm</td><td>0,99 x 0,72 mm</td><td>0,107 mm³</td></tr></table> <table><tr><td></td><td colspan="3">Hold-downs</td></tr><tr><td>Stencil thickness</td><td>PCB pad size</td><td>proposal stencil aperture size</td><td>calculated solder paste volume</td></tr><tr><td>120 µm</td><td>2,5 x 1,2 mm</td><td>2,45 x 1,15 mm</td><td>0,338 mm³</td></tr><tr><td>150 µm</td><td>2,5 x 1,2 mm</td><td>2,25 x 1,08 mm</td><td>0,365 mm³</td></tr></table> If a stencil with lower thickness shall be used, please insure the minimum required solder paste volume by enlarging the stencil aperture. Depending on the PCB design, the solder depostion may protrude the PCB pads. But to achieve a good sealing during solder paste printing and to reduce the cleaning interval of the stencil, the aperture should be smaller than the PCB pad about 10% or 25µm encircling.					Signal pins			Stencil thickness	PCB pad size	proposal stencil aperture size	calculated solder paste volume	120 µm	1,1 x 0,8 mm	1,05 x 0,75 mm	0,095 mm³	150 µm	1,1 x 0,8 mm	0,99 x 0,72 mm	0,107 mm³		Hold-downs			Stencil thickness	PCB pad size	proposal stencil aperture size	calculated solder paste volume	120 µm	2,5 x 1,2 mm	2,45 x 1,15 mm	0,338 mm³	150 µm	2,5 x 1,2 mm	2,25 x 1,08 mm	0,365 mm³								
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C	INSULATOR MATERIAL <table><tr><td>Material</td><td>LCP (liquid crystalline polymer)</td></tr><tr><td>Color</td><td>Black</td></tr><tr><td>UL classification</td><td>UL94-V0</td></tr><tr><td>Material group acc. IEC 60664-1</td><td>IIIa (175 ≤ CTI < 400)</td></tr></table> CONTACT MATERIAL <table><tr><td>Contact material</td><td>Copper alloy</td></tr><tr><td>Plating termination zone</td><td>Sn</td></tr><tr><td>Plating contact sliding side</td><td>Au over PdNi (acc. to Performance level)</td></tr></table> DERATING DIAGRAM acc. to IEC 60512-5 (Current carrying capacity) The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals. The current capacity curve is valid for continuous, non interrupted current loaded contacts of connectors when simultaneous power on all contacts is given, without exceeding the maximum temperature. Control and test procedures according to DIN IEC 60512-5 derating curve at I_{max}*0,8 (IEC 60512-5-2) 							Material	LCP (liquid crystalline polymer)	Color	Black	UL classification	UL94-V0	Material group acc. IEC 60664-1	IIIa (175 ≤ CTI < 400)	Contact material	Copper alloy	Plating termination zone	Sn	Plating contact sliding side	Au over PdNi (acc. to Performance level)																										
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D	Performance level Performance level 1 (recommended for majority of applications) Initial 250 mating cycles, 10 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 ppb. Measurement of contact resistance. The remaining 250 mating cycles are subject to measurement of contact resistance and visual inspection. Visual inspection. No abrasion of the contact finish through to the base material. No functional impairment. Part number definition : 15 2 Performance level 2 Initial 125 mating cycles, 4 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 ppb. Measurement of contact resistance. The remaining 125 mating cycles are subject to measurement of contact resistance and visual inspection. Visual inspection. No abrasion of the contact finish through to the base material. No functional impairment. Part number definition : 15 6 Performance level S4 Defined contact surface of min. 0,06 µm Au over 0,7+0,2µm PdNi Part number definition : 15 5																																														
E	<table><tr><td rowspan="2"></td><td rowspan="2">All rights reserved Department EC PD - CN</td><td rowspan="2">Created by ZHUANGJ</td><td rowspan="2">Inspected by LUOK</td><td rowspan="2">Standardisation HOFFMANN</td><td rowspan="2">Date 2018-05-21</td><td rowspan="2">State Final Release</td><td rowspan="2">Doc-Key / ECM-Nr. 100577896/UGD/001/B 500000135280</td></tr><tr></tr><tr><td colspan="2">HARTING Electronics GmbH D-32339 Espelkamp</td><td>Type DS</td><td colspan="2">Number 15111100301</td><td>Rev. B</td><td colspan="2">Page 1/2</td></tr></table>								All rights reserved Department EC PD - CN	Created by ZHUANGJ	Inspected by LUOK	Standardisation HOFFMANN	Date 2018-05-21	State Final Release	Doc-Key / ECM-Nr. 100577896/UGD/001/B 500000135280	HARTING Electronics GmbH D-32339 Espelkamp		Type DS	Number 15111100301		Rev. B	Page 1/2																									
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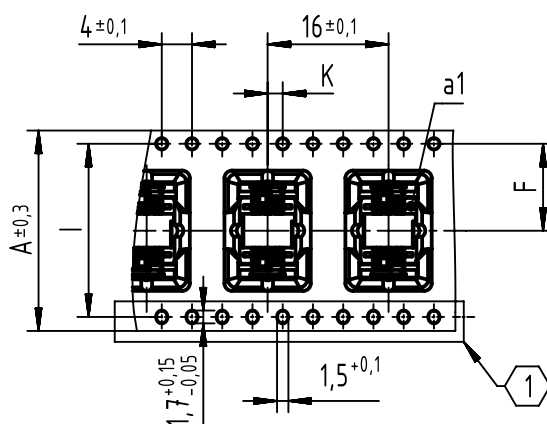
har-flex® straight male connector



TAPE LAYOUT & PACKAGING

Tape acc. to IEC 60286-3

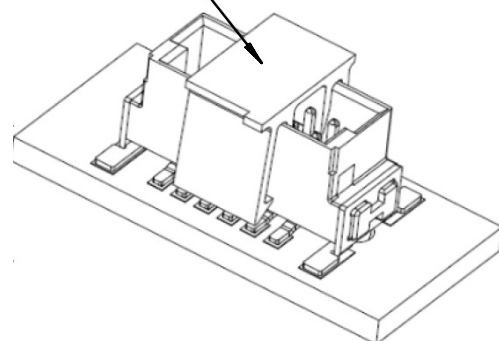
Reel off direction



Tape dimensions:	A	F	I	K
poles 06 to 12	24,0	11,5±0,1	-	2±0,1
poles 14 to 20	32,0	14,2±0,1	28,4	2±0,1
poles 22 to 40	44,0	20,2±0,15	40,4	2±0,15
poles 42 to 56	56,0	26,2±0,15	52,4	2±0,15
poles 58 to 80	72,0	34,2±0,3	68,4	2±0,2
poles 82 to 100	88,0	42,2±0,3	84,4	2±0,2

1 NO DOUBLE SPROCKET HOLES FOR 06, 08, 10 AND 12 POLE NUMBERS (TAPE SIZE 24)

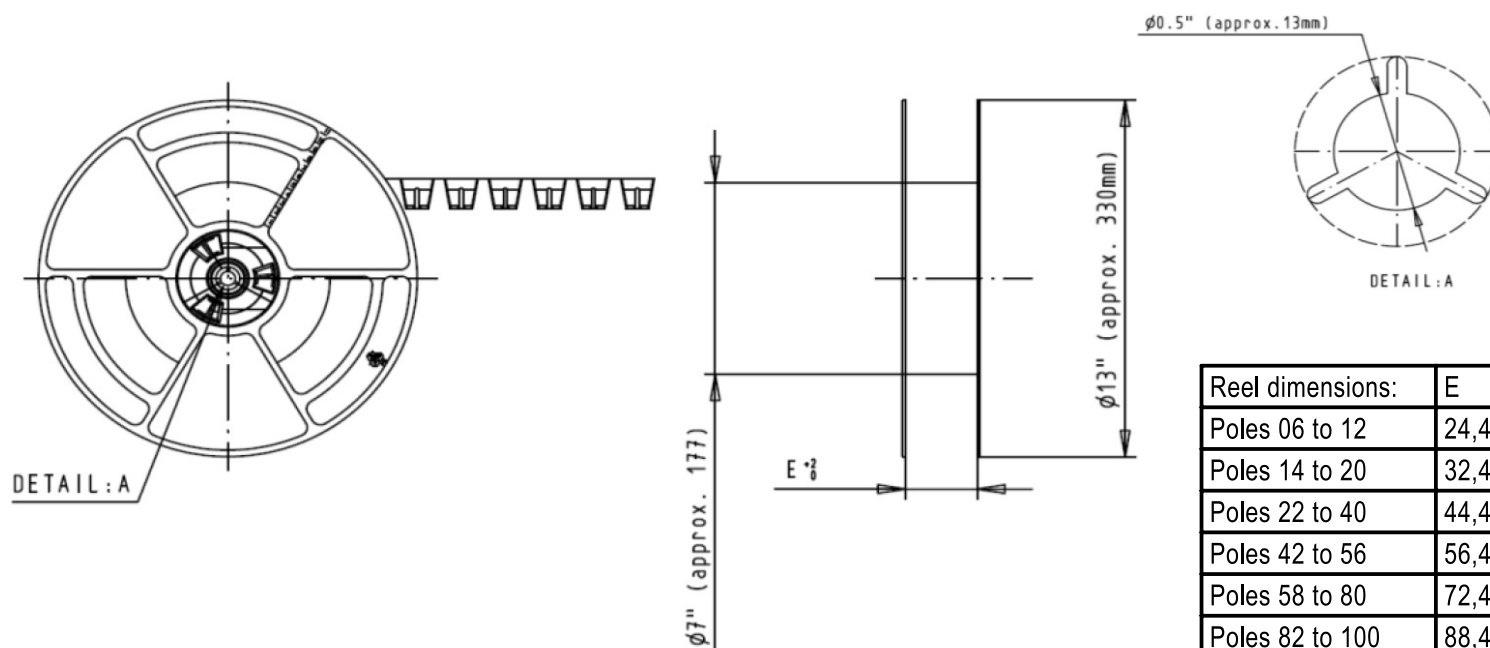
Pick & place pad 6,4±0,1 x 4,5±0,1



Packaging indices ("XXX" in part number)

Index	Packaging unit	Packaging
000	280	Tape & reel
333	1	Tape

REEL DIMENSIONS

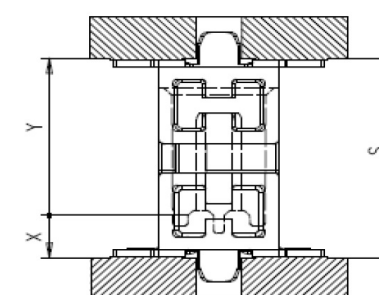


Reel dimensions:	E
Poles 06 to 12	24,4
Poles 14 to 20	32,4
Poles 22 to 40	44,4
Poles 42 to 56	56,4
Poles 58 to 80	72,4
Poles 82 to 100	88,4

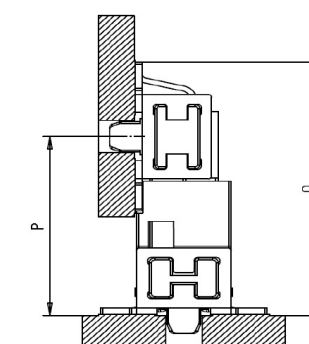
APPLICATION INFORMATION

S	14mm				
	13mm				
	12mm				
	11mm				
	10mm				
	9mm				
	8mm				
X & Y	stacking heights	male 1.75mm female 6.25mm	male 3.25mm female 6.25mm	male 1.75mm female 9.05mm	male 3.25mm female 9.05mm
S	PCB distance	8mm - 9.5mm	9.5mm - 11mm	10.8mm - 12.3mm	12.3mm - 13.8mm
	part numbers	15 11 ... 15 21 ...	15 12 ... 15 21 ...	15 11 ... 15 22 ...	15 12 ... 15 22 ...

straight female



angled female



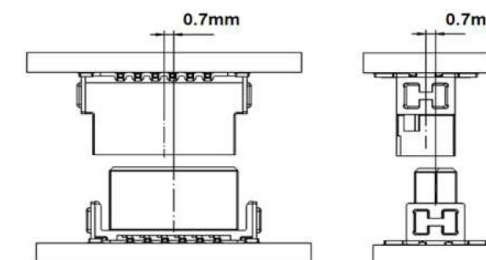
straight male

3,25	9,05	12,3	13,8
1,75	9,05	10,8	12,3
3,25	6,5	9,5	11
1,75	6,25	8	9,5
X	Y	Smin	* Smax

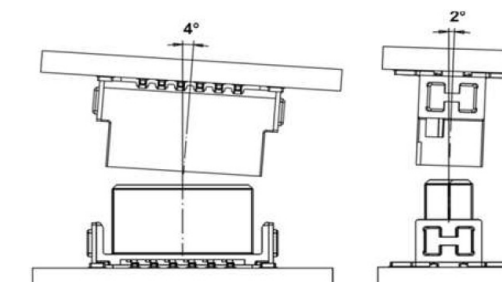
3,25	10,25	14,08
1,75	8,75	12,58
X	P min.	0

*Smax = Smin + 1.5 wiping length with additional contact overlap security

Admissible inclination



Admissible mismatching



All Dimensions in mm
Original Size DIN A3

Scale
1:1

Free size tol.

Ref.

Sub.



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Department EC PD - CN

Created by
ZHUANGJ

Inspected by
LUOK

Standardisation
HOFFMANN

Date
2018-05-21

State
Final Release

Title
har flex male stacking height 1.75 and 3.25

Doc-Key / ECM-Nr.
100577896/UGD/001/B
500000135280

HARTING Electronics GmbH

D-32339 Espelkamp

Type
DS

Number
15111100301

Rev.
B

Page
2/2

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

HARTING:

<u>15111002601000</u>	<u>15121002601000</u>	<u>15110062601000</u>	<u>15110082601000</u>	<u>15110102601000</u>	<u>15110122601000</u>
<u>15110142601000</u>	<u>15110162601000</u>	<u>15110182601000</u>	<u>15110202601000</u>	<u>15110222601000</u>	<u>15110242601000</u>
<u>15110262601000</u>	<u>15110282601000</u>	<u>15110302601000</u>	<u>15110322601000</u>	<u>15110362601000</u>	<u>15110382601000</u>
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<u>15110542601000</u>	<u>15110562601000</u>	<u>15110582601000</u>	<u>15110602601000</u>	<u>15110622601000</u>	<u>15110642601000</u>
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<u>15110902601000</u>	<u>15110922601000</u>	<u>15110942601000</u>	<u>15110962601000</u>	<u>15110982601000</u>	<u>15120062601000</u>
<u>15120082601000</u>	<u>15120102601000</u>	<u>15120122601000</u>	<u>15120142601000</u>	<u>15120162601000</u>	<u>15120182601000</u>
<u>15120202601000</u>	<u>15120222601000</u>	<u>15120242601000</u>	<u>15120262601000</u>	<u>15120282601000</u>	<u>15120302601000</u>
<u>15120322601000</u>	<u>15120342601000</u>	<u>15120362601000</u>	<u>15120382601000</u>	<u>15120402601000</u>	<u>15120422601000</u>
<u>15120442601000</u>	<u>15120462601000</u>	<u>15120482601000</u>	<u>15120502601000</u>	<u>15120522601000</u>	<u>15120542601000</u>
<u>15120562601000</u>	<u>15120582601000</u>	<u>15120602601000</u>	<u>15120622601000</u>	<u>15120642601000</u>	<u>15120662601000</u>
<u>15120682601000</u>	<u>15120702601000</u>	<u>15120722601000</u>	<u>15120742601000</u>	<u>15120762601000</u>	<u>15120782601000</u>
<u>15120802601000</u>	<u>15120822601000</u>	<u>15120842601000</u>	<u>15120862601000</u>	<u>15120882601000</u>	<u>15120902601000</u>
<u>15120922601000</u>	<u>15120942601000</u>	<u>15120962601000</u>	<u>15120982601000</u>	<u>15120162601333</u>	

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Офис по работе с юридическими лицами:

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